

2.2 Pin Descriptions

Pin Name	Description
PACK+	Pack positive terminal
PACK-	Pack negative terminal
CELL+	Cell positive terminal
CELL-	Cell negative terminal
TERM	Thermistor input that leads to IC TS pin
SDA	I ² C communication data line
SCL	I ² C communication clock line
HDQ	Single-wire communication line
VSS	Signal return for communication line

3 Circuit Module Physical Layouts, Bill of Materials, and Schematic

This section contains the printed-circuit board (PCB) layout, bill of materials, assembly drawings, and schematic for the bq27741 circuit module.

3.1 Board Layout

This section shows the printed-circuit board (PCB) layers (Figure 1 through Figure 4), assembly drawing, and schematic for the bq27741 module.

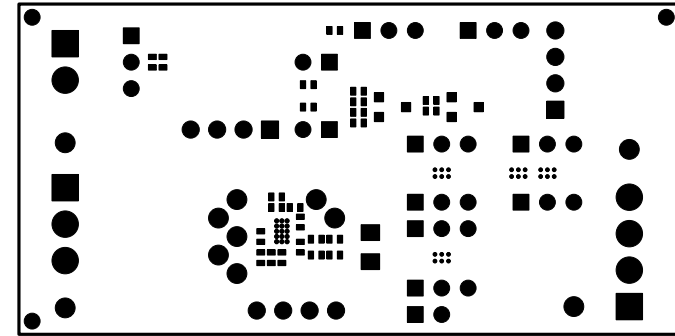


Figure 2. Top Assembly

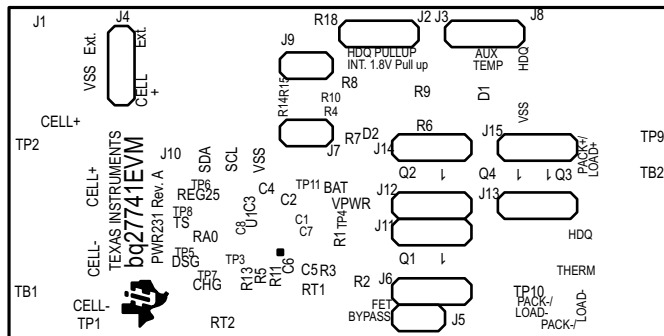


Figure 1. bq27741EVM Layout, Silk Screen

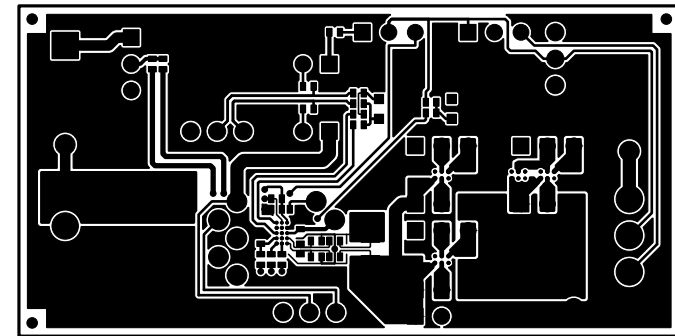


Figure 3. Top Layer

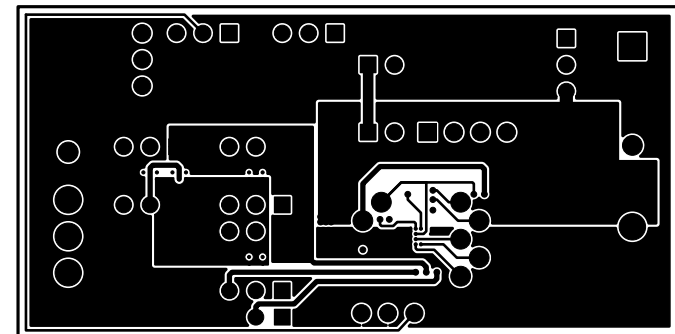


Figure 4. Bottom Layer

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